



PATENT
81716.0117

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of:

Yoshihiro BASHO, et al

Serial No: 10/758,302

Filed: January 15, 2004

For: Heat Releasing Member, Package for
Accommodating Semiconductor Element
and Semiconductor Device

Date of NOA: March 21, 2005

Art Unit: 2815

TRANSMITTAL OF ISSUE FEE

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P.O. Box 1450
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Wendy McLaren

Name

Wendy McLaren

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6/3/05

Date

Dear Sir:

In response to the Notice of Allowance dated March 21, 2005, enclosed are the following:

- ☒ Form Part B - Issue Fee Transmittal, Advance Order for 10 patent copies and a check in the amount of \$ 1730.00 in payment of the Issue Fee, Publication Fee and Advance Order.
- ☒ Comments on Statement of Reasons for Allowance.

The Commissioner is hereby authorized to charge any deficiency in payment or credit any overpayment to Deposit Account No. 50-1314. A copy of this Transmittal is enclosed.

Respectfully submitted,

HOGAN & HARTSON L.L.P.

Date: June 3, 2005

By:

Lawrence J. McClure

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Patent Application No. 10/758,302
Attorney Docket No. 81716.0117

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Dear Sir:

In the Notice of Allowance dated March 21, 2005, the Office stated that:

“The reference (s) of record do not teach or suggest either singularly or in combination at least one limitation of . . . “wherein in the heat releasing member, a plurality of through metal members made a plate like substrate made of a matrix of tungsten or molybdenum and copper to another surface, copper layers are joined at least to one and other surfaces of a portion in which the through metal members of the substrate are buried, and a cross section area of each of the through metal members is gradually increased from the center side of the substrate to a joint portion with the copper layers.”

Applicant notes that the quoted portion of claim 10 is inaccurate in that it omits a limitation contained in claim 10. Namely, the quoted section of paragraph 10 should read:

“wherein in the heat releasing member, a plurality of through-metal members made of a copper are buried from one surface of the mounting portion of a plate-like substrate made of a matrix of tungsten or molybdenum and copper to another surface, copper layers are joined at least to one and other surfaces of a portion in which the through-metal members of the substrate are buried, and a cross-section area of each of the through-metal members is gradually increased from the center side of the substrate to a joint portion with the copper layers.” (underlining added to show omitted limitation.)

Respectfully submitted,

HOGAN & HARTSON L.L.P.

Date: June 3, 2005

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